LØGITECH
Materials Technologists & Engineers

CONSUMABLE PRODUCT CATALOGUE

PRECISION MATERIALS PROCESSING TECHNOLOGIES

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CONSUMABLE PRODUCT CATALOGUE

Logitech consumables are carefully chosen to work in unison with our sample processing systems to obtain optimum performance and maximise system lifespan.

Through our extensive experience in materials processing, we have gained a tremendous amount of knowledge of consumables and how best to use them.

As a result, we source only the highest quality products and rigorously test them on the quality of result produced and on the suitability for the many precision materials processing applications for which Logitech systems are used.

In fact, our selection process is so thorough that we only use Logitech consumables in our own laboratory.

Browse our wide range of consumable products and place your order online at: store.logitech.uk.com

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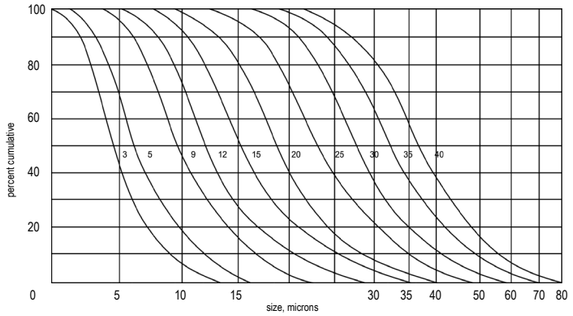
CALCINED ALUMINIUM OXIDE POWDERS

Logitech Calcined Aluminium Oxide Powders are produced using a unique process which grades particles in sizes and shape more closely than possible by normal means. This makes it especially effective when used on hard materials such as ceramics, silicon and hardened steel.

CALCINED ALUMINIUM OXIDE LAPPING POWDERS

PARTICLE SIZE DISTRIBUTION CURVES



The particles produced by this process are flat, and tend to lie parallel to the surface being processed. Working pressure is, therefore, more evenly spread, breakdown of particles is reduced and abrasiveness is retained for a longer period. Due to the close grading and flat particle shape, calcined aluminium oxide powders are suitable for a wide range of precision lapping and polishing operations and offer many advantages.

These include:

- Improved Surface Finish - by keeping the lapping / polishing time constant, substantial surface finish improvements can be obtained.

- Increased Particle Size - Due to the surface quality improvements, larger particle sizes can be used to produce the same quality of components. This provides distinct improvements in normal process times and leads to greater production output in addition to higher quality surfaces

Code	Micron Size	Pack Size	Description
0CON-007	1	5 kg	Suitable for high precision optical component polishing, & as the final polishing stage for certain types of thin rock section.
0CON-008	3	5 kg	The most commonly used particle size. Suitable for a wide range of fine lapping applications with semiconductor and optical materials.
0CON-009	9	5 kg	Used for rapid stock removal on delicate semiconductor materials, such as GaAs and optical components.
0CON-010	12	5 kg	Applications include initial lapping of piezo-electric crystals prior to final lapping with 3 and 1 micron abrasives.
0CON-011	15	5 kg	Suitable for initial lapping of precision optical components and for final polishing of “hard” material components.
0CON-012	20	5 kg	Applications include “backlapping” of silicon wafers and fine lapping of quartz and sapphire components.
0CON-013	30	5 kg	Used for coarser lapping of components such as mechanical seals, or with semiconductor and optical materials where high stock removal rates are required.
0CON-030	50	5 kg	Used for coarser lapping of components such as mechanical seals, or with semiconductor and optical materials where high stock removal rates are required.

SILICON CARBIDE POWDERS

Silicon Carbide is a lapping/polishing compound suitable for the fine lapping of a range of geological, semiconductor and optical materials.

SILICON CARBIDE LAPPING POWDERS

Logitech Silicon Carbide Powders are manufactured for use in high precision lapping and polishing operations. Supplied in a wide range of grit sizes, these high quality abrasive powders can be used where repeatability of material removal rate is required.

Typical applications include:

- Thin rock section production
- Silicon wafer backthinning
- Processing of ferrites and other ceramic components
- Calcified tissue thin section production

Silicon Carbide abrasive is also recommended for lapping the chuckface of the Logitech Precision Lapping and Polishing Jigs and fixtures to restore chuckface parallelism.

TYPICAL CHEMICAL ANALYSIS (%)

Silicon Carbide:	97.60
SiO_2:	0.60
Si:	0.80
Fe:	0.20
Al:	0.30
Carbon:	0.50
Magnetic Iron:	0.04

PRODUCT DATA

Product:	Silicon Carbide Lapping Powder
Colour:	Dark grey
pH:	6.8 - 7.2
Shape:	Blocky, with sharp edges
Grading:	FEPA 42-GB-1984
Bulk Density:	FEPA 44-GB-1986
Surface Chemistry:	FEPA 26-GB-1968
Knoop100 Hard No:	2480
Specific Gravity:	3.2g/cc
Crystal Structure:	Hexagonal
Fracture:	**Conchoidal**

Code	Micron Size	Pack Size	Description
0CON-006	3	5 kg	Fine lapping / polishing compound suitable for fine lapping of a range of geological, semiconductor and optical materials (1200 grit).
0CON-001	5	5 kg	Fine lapping / polishing compound suitable for fine lapping of a range of geological, semiconductor and optical materials (1000 grit).
0CON-002	9	5 kg	Applications include petrographic thin rock section production and silicon wafer lapping (600 grit).
0CON-003	17	5 kg	Suitable for coarse lapping applications or where rapid material removal is required (400 grit).
0CON-004	29	5 kg	Mean particle size 29 microns (320 grit).
0CON-005	45	5 kg	Mean particle size 45 microns (240 grit).

FUSED ALUMINIUM OXIDE POWDERS & BORON CARBIDE POWDERS

These powders are manufactured for use in lapping operations where high precision finishes are specified on hard materials.

FUSED ALUMINIUM OXIDE LAPPING POWDERS

Logitech Fused Aluminium Oxide powders are manufactured to comply with the exacting standards required for precision lapping and optical polishing operations. Formulated for rapid stock removal, with high quality surface finish, these abrasives will perform with outstanding efficiency. They have excellent cleanliness and capillarity and are low in magnetic content.

PRODUCT DATA

Product Type:	Fused Aluminium Oxide
Colour:	Grey Brown
pH:	7.5 - 8.5
Hardness, Moh:	9.0
Grading:	FEPA 42-GB-1984
Specific Gravity:	3.8
Particle Shape:	Equi-dimensional

TYPICAL CHEMICAL ANALYSIS (%)

Aluminium Oxide:	96.00
Silica:	1.10
Iron Oxide (Fe_2O_3):	0.25
Titanium Oxide:	2.55

Code	Micron Size	Pack Size	Description
0CON-017	3	5 kg	Fine Lap
0CON-018	5	5 kg	
0CON-019	9	5 kg	
0CON-021	15	5 kg	Rough Lap

A range of micron sizes, enabling precision materials to be processed from the initial roughing stage through to fine lapping and polishing.

These powders are carefully processed to ensure correct particle size distribution. Particle shape is as uniform as the most advanced manufacturing techniques will permit.

BORON CARBIDE LAPPING POWDERS

Logitech boron carbide lapping powders are very hard abrasives filling the need for an abrasive powder which is harder than silicon carbide, but less expensive than diamond. Applications for use of boron carbide include the processing of ceramic materials, very hard optical materials such as sapphire, heat treated alloys and very hard mineral sections.

PRODUCT DATA

Product Type:	Boron Carbide
Colour:	Black
pH:	N/A
Percentage content:	98%
Density:	3.95
Particle Shape:	Granular

Code	Micron Size	Pack Size	Description
0CON-024	1000	1 kg	Fine Lap
0CON-025	600	1 kg	
0CON-026	400	1 kg	
0CON-027	320	1 kg	
0CON-028	240	1 kg	
0CON-029	180	1 kg	
0CON-514	240	5 kg	Rough Lap

A range of micron sizes, enabling precision materials to be processed from the initial roughing stage through to fine finishing.

Manufacture and quality control procedures used in the production of these powders ensure that the end product is exceptionally clean and closely sized.

ULTRA FINE ALUMINIUM OXIDE POWDERS & CERIUM OXIDE POWDERS

Logitech powders are manufactured to comply with the exacting standards required for precision lapping and optical polishing abrasives. Suitable for processing a wide variety of materials including semiconductors, precision optics and metallographic micro sections.

ULTRA FINE ALUMINIUM OXIDE POLISHING POWDERS

Logitech Ultra Fine Aluminium Oxide Polishing Powders are sub-micron powders produced in a special process using the calcination of alum. They are chemically inert, fast cutting abrasives, suitable for a wide variety of lapping / polishing plate types. All three types can be used in suspension, slurry or paste form by mixing with water.

Materials processing applications for Ultra Fine Aluminium Oxide Powders include:

- Optical Components
- Ferrite Components
- Plastics
- Metallographic Micro Sections
- Ceramics
- Electro-Optic Materials
- Semiconductor Wafers

PRODUCT DATA

Product Type:	Aluminium Oxide Powder
Colour:	White, tan or grey powder
Odour:	None
Percentage content:	95-99%
Boiling point:	2980 °C
Melting point:	2045 °C
Solubility:	Insoluble in water and solvents

Code	Micron Size	Pack Size	Description
0CON-014	0.05	2 kg	Gamma alumina: The least aggressive of the ultra fine aluminas due to the extremely small crystal size. Used for final surface polish of a wide variety of materials.
0CON-015	0.3	2 kg	Alpha alumina: Rapid cut, produces smooth mirror like finish on metal composites and ceramic surfaces. Used as a pre-polish on many surfaces or a final polish on optical materials.
0CON-016	1.0	2 kg	Alpha alumina: Provides an aggressive cutting action, and is often used for the initial surface preparation stages prior to processing with 0.3 or 0.05 micron aluminas.

CERIUM OXIDE POLISHING POWDERS

Cerium Oxide Polishing Powders are rare earth polishing media, formulated for the final polishing of materials to “optical” polishing standards. Suitable for use with pitch and polyurethane polishing plates and a wide variety of polishing cloths, these powders offer the highest quality performance and uniform surface finish on a wide range of glasses and electro-optic materials.

PRODUCT DATA

Product Type:	Cerium Oxide Powder
Colour:	Cream
Bulk Density:	1.7 ±0.2 grams/cc
Mean Particle Size:	3.0 microns ±1

Code	Micron Size	Pack Size	Description
0CON-260	0.5	1 kg	Opaline grade for high quality finishing for optical and electro-optical components.
0CON-023	3	1 kg	CC2 grade for optical polishing of standard optical and electro-optical components.

DIAMOND POLISHING POWDERS

Particularly useful for polishing small rock specimens, minerals, thin sections and metallic ores where specific lubricant carriers are required.

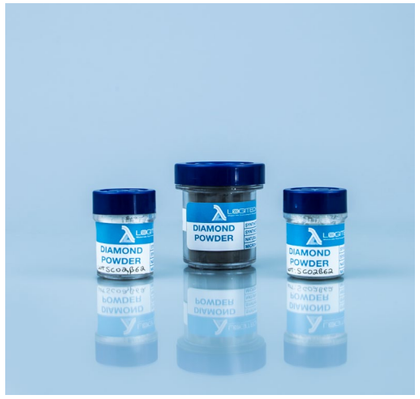
DIAMOND POLISHING POWDERS

Logitech Diamond Polishing Powders offer the ultimate in quality and economy of operation and can be used with a wide variety of soft metal polishing plates and polishing cloths. Mix with polishing carrier fluids.

Polycrystalline particles breaks down more readily than their monocrystalline counterparts, resulting in more crystal facets being revealed. This, in turn, produces a faster polishing process due to the sharper edges.

Applications include:

- Geological Specimens
- Laser Rods
- Silicon Carbide
- Sapphire/Gallium Nitride
- Metals
- CVD Diamond



PRODUCT DATA

Product Type:	Diamond
Colour:	White
Specific gravity:	3.513
Soluble:	No

Code	Micron Size	Pack Size	Description
0CON-276	1	4g	Economic choice for thin section polishing. Finest polish finish.
0CON-277	3	4g	Economic choice for thin section polishing. Fine polish finish.
0CON-279	1	4g	Economic choice for thin section polishing. Rapid stock removal.
0CON-278	6	4g	Polycrystalline diamond is more efficient for polishing. Finest polish finish.
0CON-280	3	4g	Polycrystalline diamond is more efficient for polishing. Fine polish finish.
0CON-281	6	4g	Polycrystalline diamond is more efficient for polishing. Rapid stock removal.
0CON-282	50	20g	Lapping of ultra hard ceramics and CVD diamond films.
0CON-322	25	20g	Lapping of sapphire substrates.
0CON-325	15	20g	Lapping of sapphire substrates.
0CON-328	9	20g	Lapping of sapphire substrates.

CHEMCLOTH POLISHING CLOTHS

Polyurethane based sutiable for final polishing of delicate semiconductor materials such as Gallium Arsenide with Chemlox polishing fluid.

CHEMCLOTH POLISHING CLOTHS

Logitech Chemcloth polishing cloths are designed to satisfy the exacting requirements of Chemical Mechanical Polishing (CMP). The black napped urethane surface layer is intrinsic to the substrate giving superior nap strength and longer pad life. Incorporating a vertically oriented pore structure with a compressible substrate which is designed to instantly recover from compression and thereby enhances slurry flow.

Chemcloth polishing cloths are supplied with a protected self-adhesive backing and each pack is hermetically sealed in a polythene sachet.

Chemcloth is ideally suited to a variety of polishing processes including:

- Production polishing due to the cloth's superior wear resistance and subsequent long life.
- Finishing under corrosive acid and alkaline conditions because of its ability to produce perfect polishes in less time.
- High speed polishing operations due to its superior nap strength

Code	Diameter	Pack Size	Machine Compatability	Description
0CON-350	8"/200mm	10	Compact 50 System	
0CON-352	12"/300mm	10	PM6	
0CON-353	14"/350mm	10	LP50/CP3000	
0CON-471	16"/400mm	10	Akribis-air/Tribo	
0CON-354	18"/450mm	10	CP4000	
0CON-356	20"/508mm	10	CDP	
0CON-355	22"/560mm	10	DP1	
0CON-357	24"/610mm	10	Orbis	
0CON-358	27.6"/700mm	1	DP4	
0CON-505	16"/400mm	10	Pre-grooved cut to size, compatible with various systems	

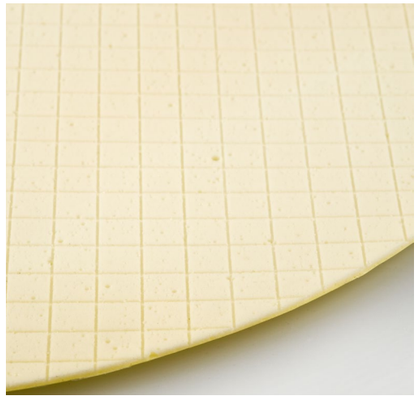
Chemcloth pads are polyurethane based and incorporate a vertically orientated pore structure with a compressible substrate which is designed to instantly recover from compression and thereby enhances slurry flow. This reduces pad loading and increases pad life.

Suitable for polishing delicate semiconductor materials such as Gallium Arsenide with Chemlox polishing fluid.

All Logitech polishing clothes are supplied in self adhesive backed form.

POLISHING CLOTHS & PADS

The Logitech range of polishing cloths provides a comprehensive selection of materials for fine surface polishing of the widest range of sample types.



CHEMICAL MECHANICAL POLISHING (CMP) CLOTHS & PADS

Logitech Chemical Mechanical Polishing (CMP) cloths are manufactured specifically for CMP processes and are used on various systems including the PM6, LP50, Tribo and Orbis.

Carefully chosen because of texture and for their capability to retain abrasive on the cloth surface in an efficient and economic manner. This ensures that samples are produced to the highest quality of surface finish while obtaining the best possible surface flatness.

Code	Diameter	Pack Size	Type
0CON-399	12”/300mm	5	EP1-P
0CON-398	12”/300mm	5	EP1-G
0CON-387	12”/300mm	5	EP2-P
0CON-386	12”/300mm	5	EP2-G
0CON-401	14”/350mm	5	EP1-P
0CON-400	14”/350mm	5	EP1-G
0CON-389	14”/350mm	5	EP2-P
0CON-388	14”/350mm	5	EP2-G
0CON-481	16”/400mm	1	EP1-P
0CON-482	16”/400mm	1	EP1-G
0CON-483	16”/400mm	1	EP2-P
0CON-484	16”/400mm	1	EP2-G
0CON-377	20”/508mm	1	EP1-P
0CON-367	20”/508mm	1	EP1-G
0CON-370	22”/550mm	1	EP1-G
0CON-385	22”/550mm	1	EP2-G
0CON-487	24”/600mm	1	EP1-P
0CON-488	24”/600mm	1	EP1-G
0CON-489	24”/600mm	1	EP2-P
0CON-490	24”/600mm	1	EP2-G
0CON-392	28”/700mm	1	EP1-G
0CON-393	28”/700mm	1	EP2-G

EP1
The EP1 has a foamed elastomer structure with controlled cells. Its unique structure and high hardness improves planarity and is designed for optimum polishing of Silicon, Sapphire and optical materials.
Shore A Hardness 97

EP2
The EP2 has a micro-cellular structure that enables it to act in a “sponge like” manner, while maintaining the hardness and flatness. Pads are supplied with a pressure sensitive adhesive backing, excellent flatness control and fast polishing.
Shore A Hardness 86

P (Plain) Designed for surfaces less than 20cm²
G (Grooved) Designed for surfaces greater than 20cm²

POLISHING CLOTHS & PADS

Perfect for delivering optimal removal rates, with low global non-uniformity & defects.

CHEMICAL MECHANICAL POLISHING (CMP) CLOTHS & PADS

These cloths are suitable for various CMP applications (e.g. oxide, nitride and copper). They have an open pore structure with various urethane compression selectibility compositions. They are ideal for low to medium pressure applications.

Code	Diameter	Pack Size	Machine Compatibility	Pad Hardness	Type
0CON-360	8”/200mm	10	Compact 50	Shore A - 92	GC
0CON-361	10”/250mm	10	Compact 50	Shore A - 92	GC
0CON-362	12”/300mm	10	PM6/PM5	Shore A - 92	GC
0CON-342	12”/300mm	5	PM6/PM5	Shore D - 57	IC1000
0CON-363	14”/350mm	10	LP50/CP3000	Shore A - 92	GC
0CON-343	14”/350mm	5	LP50	Shore D - 57 Shore A - 67	IC1000 Stacked with Suba IV
0CON-323	14”/350mm	5	LP50	Shore A - 68	SBX
0CON-474	16”/400mm	1	Akribis-air/Tribo	Shore D - 57	IC1000
0CON-473	16”/400mm	1	Akribis-air/Tribo	Shore A - 67	SBIV
0CON-472	16”/400mm	1	Akribis-air/Tribo	Shore A - 68	SBX
0CON-364	18”/450mm	10	CP4000	Shore A - 92	GC
0CON-381	20”/508mm	1	CDP	Shore D - 57	IC1000
0CON-382	20”/508mm	1	CDP	Shore A - 67	SBIV
0CON-365	22”/560mm	10	DP1	Shore A - 92	GC
0CON-479	24”/600mm	1	Orbis	Shore D - 57	IC1000
0CON-478	24”/600mm	1	Orbis	Shore A - 67	SBIV
0CON-477	24”/600mm	1	Orbis	Shore A - 68	SBX
0CON-383	28”/700mm	1	DP4	Shore A - 67	SBIV

Suba IV (SBIV)
Suba IV pads feature an open pore structure and a less aggressive urethane composition that other pads. They are ideal for low to medium pressure applications with fragile crystals or delicate surfaces. Often used as a base pade in conjunction with a IC1OOO pad.

Suba X (SBX)
Suba X is a denser, harder pad with a smaller pore structure than our Suba IV pad. It is often used for polishing glass, quartz or ceramics with consistent, reproducible results.

IC1000
The IC1000 pad is made of rigid, microporous polyurethane. This allows it to planarize across wide gaps, providing excellent removal rates and localised uniformity. The small pore structure works with slurries to minimize scratching and provide optimum polishing performance.

Geochem (GC)
The Geochem cloth is firm, dense and non-woven polishing cloth with absrobent fibres, providing a high level of flatness. This cloth is often used with a diamond slurry for polishing geological samples or chemical polishing of III-V semiconductor materials.

POLISHING CARRIER FLUID & POLISHING SUSPENSIONS

- Colloidal silica, sub-micron alumina and chemo-mechanical polishing suspensions.

POLISHING SUSPENSIONS

Logitech Polishing Suspensions have been developed to suit a wide range of polishing applications in the semiconductor and opto-electronic industries. Both of these products produce polishes of the highest quality and are produced at our own purpose-built materials processing laboratories.

PRODUCT DATA

Product Type: SF1 Polishing Fluid
Colour: Opaque
pH: (At G/1 H_2O) 9.2-10.1
Boiling Point: 100 deg °C (212 °F)

Product Type: Chemlox Polishing Fluid
Colour: White Suspension
pH: 11.4
Boiling Point: 100 deg °C (212 °F)

Product Type: Logipol CS60
Colour: White Suspension
pH: 8.5
Boiling Point: 100 deg °C (212 °F)

Product Type: Logipol CMD30
Colour: Semi-opaque
pH: 6-8
Boiling Point: 100 deg °C (212 °F)

Product Type: Logipol 35
Colour: White Suspension
pH: 11.5-12.5
Boiling Point: 100 deg °C (212 °F)

Code	Type	Quantity	Description
0CON-141	Chemlox	4 litres	Sodium hypochlorite based polishing fluid, with a high pH. Suitable for chemo-mechanical polishing of GaAs, InP and similar semiconductors.
0CON-140	SF1	5 litres	Alkaline colloidal silica. Suitable for polishing silicon wafers and a wide range of optical / electro-optical components.
0CON-137	SF1	25 litres	Alkaline colloidal silica. Suitable for polishing silicon wafers and a wide range of optical / electro-optical components.
0CON-511	Logipol CS60	4.5 litres	Logipol 60nm Colloidal Silica polishing soltuion for polishing III-V semiconductor materials including Indium Phosphide
0CON-510	Logipol CS60	22.7 litres	Logipol 60nm Colloidal Silica polishing soltuion for polishing III-V semiconductor materials including Indium Phosphide
0CON-509	Logipol CMD 30	3.78 litres	Logipol CMD30 3 micron polishing fluid used in polishing hard material substrates including Silicon Carbide/Silicon/ Alumina/Ceramic
0CON-508	Logipol CMD 30	18.9 litres	Logipol CMD30 3 micron polishing fluid used in polishing hard material substrates including Silicon Carbide/Silicon/ Alumina/Ceramic
0CON-507	Logipol CS20 Polishing Fluid	2 litres	Logipol CS20 20nm Colloidal Silica polishing fluid is used in polishing/planarisation of IC's/dies
0CON-493	Logipol 35	4 litres	Logipol 35 polishing fluid is a Sodium Hypochlorite based additive for III-V and II-VI semiconductor wafer polishing - can be mixed with Alumina or Colloidal Silica based polishing slurries to improve polishing rate

POLISHING CARRIER FLUID & POLISHING SUSPENSIONS

- Alcohol, oil based fluids and extenders for use with water soluble materials.

POLISHING CARRIER FLUIDS

Logitech Ethane Diol contains excellent properties to assist the polishing process of water soluble materials. Ethane Diol is an effective slurry carrier with many powders including diamond, silicon carbide and aluminium oxide.

PRODUCT DATA

Product: Logitech Ethane Diol
Colour: Colourless viscous liquid
Gravity: 1.11
Boiling Point: 197 deg °C (386 °F)
Freezing Point: -12.3 deg °C (9.86 °F)

Code	Quantity	Description
0CON-128	5 litres	Oil Based Suspension Fluid. Used in conjunction with Diamond Powder for geological thin section applications.
0CON-133	5 litres	Ethane Diol. For use with silicon carbide and aluminium oxide powders when processing water soluble materials.
0CON-134	5 litres	Ethane Diol Plus. Has a higher purity than standard ethane diol and contains a reduced (1%) water content for use with water soluble materials.
0CON-135	5 litres	K-43 Polishing Fluid. Suitable for use with diamond or aluminium oxide powders when polishing water soluble materials and IR materials.

LOGIPOL HAZE INHIBITOR

Logipol Haze Inhibitor is a haze-inhibiting polishing additive specifically formulated to help limit the time required for haze removal during the polishing process, used in the post polishing process for Silicon and other II-IV and III=-V materials. Can be used to store wafers in a wet clean room environment. It can also be used in Static/Dynamic Templates to hold the wafer on the napcon insert during the polishing process.

Code	Quantity	Description
0CON-501	3.8 litres	Used in the polishing process of Silicon and other II-IV and III-V materials.
0CON-502	19 litres	

DIAMOND SUSPENSIONS & HYPER DIAMOND SUSPENSIONS

Logitech Diamond Suspensions are high performance water based diamond suspensions containing exclusively polycrystalline diamonds.

DIAMOND SUSPENSIONS

Logitech Diamond Suspensions containing exclusively polycrystalline diamonds, used to provide the highest quality preparation, faster removal rates and a finer finished surface. They are stable and retain their properties from the beginning of the preparation to the very end. They offer very good materials removal and do not settle or clog the dosing system.

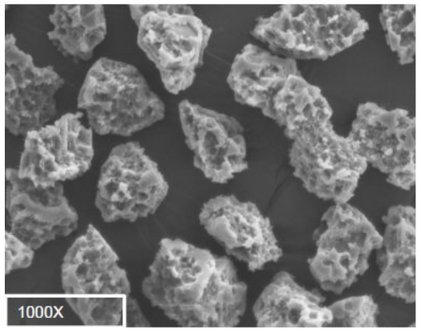
Code	Micron Size	Pack Size	Description
0CON-315	1	500ml	Contains high quality polycrystalline diamonds. Alcohol free. Constant suspension.
0CON-314	3	500ml	
0CON-313	5	500ml	

LOGIPOL HYPER DIAMOND SUSPENSION (HDS)

Logipol Hyper Diamond Suspension designed for lapping & polishing applications proves extremely effective on hard material substrates including:

- Silicon Carbide
- Silicon
- Alumina
- Ceramics

Each particle has more cutting points and achieves higher material removal rates, small cutting points produce lower surface roughness, rough particle surface improves retention in any bond system and consistent friability ensures particles will not crush under the load of lapping and polishing for extended life.

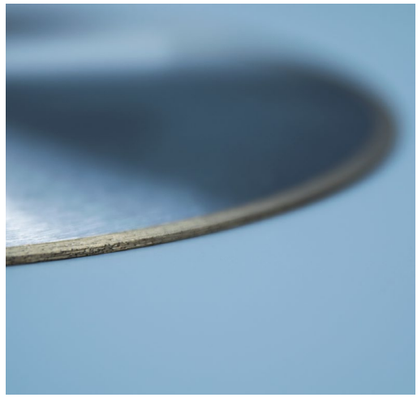


LOGIPOL HDS PARTICLES

Code	Micron Size	Pack Size	Description
0CON-513	2-4	1 ltr	Suitable for hard material substrates Silicon Carbide, Silicon, Alumina, Ceramics.
0CON-512	1-3	1 ltr	

SAW BLADES & CUTTING WIRES

Logitech supply a wide range of saw blades and cutting wires for use with our precision saws, designed to meet a wide range of requirements within an extremely diverese range of materials processing applications.



SAW BLADES & CUTTING WIRES

The range of saws produced by Logitech cater for the requirements of the small scale laboratory, producing high quality thin sections, through to batch production of valuable crystal materials.

The main application areas include:

- Geology and Thin Rock Section production
- Semiconductors i.e. Gallium Arsenide
- Electro-optics i.e. Lithium Niobate and similar materials
- Optics i.e. Laser Rods, Nd:YIG, Nd:YAG etc.

Code	Diameter	Pack Size	Machine	Description
0CON-203	8”/200mm	1	AXL1 Saw	Diamond rimmed annular blade for the AXL1 saw.
0CON-205	10”/250mm	1	CS10 Saw	Diamond Cut-off blade. Blade thickness 1.6mm, 15.9mm arbor for the CS10 saw.
0CON-206	8”/200mm	1	CS30 Saw	Diamond cut-off blade, suitable for cutting most common rock types on the CS30 saw. Blade thickness 1.5mm, 22mm arbor.
0CON-208	6”/150mm	1	Model 15 Saw	Thin rimmed diamond blade for the Model 15 saw. Blade thickness 0.25mm, 12.7mm arbor.
0CON-209	6”/150mm	1	Model 15 Saw	Rimmed diamond blade for the Model 15 saw. Blade thickness 0.4mm and t-size 0.5mm with 12.7mm arbor.
0CON-210	4”/100mm	1	Model 15 Saw	Thin rimmed diamond blade for the Model 15 saw. Blade thickness 0.3mm, t-size 0.4mm with 12.7mm arbor.
0CON-215	4”/100mm	1	Model 15 Saw	Silicon Carbide blade, 180 grit for the Model 15 saw. Blade thickness 0.3mm, 12.7mm arbor.
0CON-216	6”/150mm	1	Model 15 Saw	Silicon Carbide blade, 320 grit for the Model 15 saw. Blade thickness 0.5mm, 12.7mm arbor.
0CON-219	0.3mm	5	Model 15 Saw	60 micron diamond wire, for minimal damage cutting of delicate crystal materials
0CON-220	0.2mm	5	Model 15 Saw	60 micron diamond wire, for minimal damage cutting of delicate crystal materials
0CON-283	10”/250mm	1	APD1 Saw	Diamond rimmed annular blade for the APD1 saw.
0CON-284	12”/300mm	1	APD1 Saw	Diamond rimmed annular blade for the APD2 saw.
0CON-294	10”/250mm	1	APD1 Saw	Diamond rimmed annular blade for the APD1 saw, 320 grit.
0CON-320	6”/150mm	1	APD1 & APD2 Saw	Diamond rimmed blade (12.7mm bore) for APD1 and APD2 saws.
0CON-321	4”/100mm	1	APD1 & APD2 Saw	Diamond rimmed blade (12.7mm bore) for APD1 and APD2 saws.
0CON-329	12”/300mm	1	GTS1 Saw	Diamond cut-off blade, suitable for cutting most rock types on the GTS1 saw.
0CON-330	6”/150mm	1	APD2 Saw	Diamond rimmed blade (12.7mm bore) for APD2 saws. Blade thickness 0.2mm.
0CON-230	0.2mm	1	APD1 Saw	Steel cutting wire for AWS1 Abrasive Wire Saw.
0CON-231	0.25mm	1	APD1 Saw	Steel cutting wire for AWS1 Abrasive Wire Saw.
0CON-515	0.37mm	5	Model 15 Saw	Diamond cutting wire 60 micron for high quality cutting with improved parallelism and perpendicularity. For Sapphire and Opto-electronic applications.
0CON-516	0.23mm	5	Model 15 Saw	Diamond cutting wire 60 micron for high quality cutting with improved parallelism and perpendicularity. For Sapphire and Opto-electronic applications.

MOUNTING MEDIA

- Epoxy Resins for sample impregnation for permanent bonding applications
- UV Resins for fast curing
- A range of bonding waxes for low/high temperature mounting and aggressive chemical environments
- Thermoplastic coverslip mounting media and bonding resins

TEMPORARY & PERMANENT MOUNTING ADHESIVES

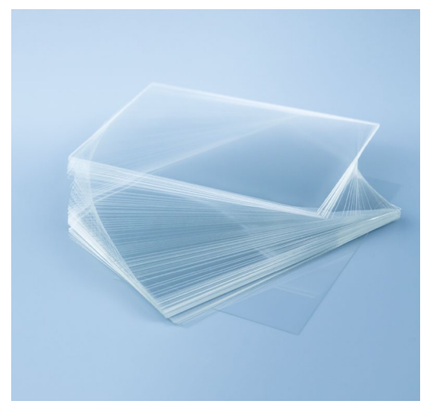
Code	Type	Pack Size	Bond Type	Description
0CON-185	Epoxy Pack 301	454g	Permanent	2 part epoxy resin, RI 1.54. Suitable for a wide range of mounting and impregnation applications including thin rock section bonding.
0CON-185-10	Epoxy Pack 301	4.5kg	Permanent	2 part epoxy resin, RI 1.54. Suitable for a wide range of mounting and impregnation applications including thin rock section bonding.
0CON-186	UV Resin	50ml	Temporary	Ultraviolet light curing urethane acrylic resin. Suitable for temporary, controlled thickness bonding applications.
0CON-193	Wax	4 ingots	Temporary	Thin Film Bonding Wax, 50-55 °C melting point, is ideal for holding substrates in place during slicing, dicing.
0CON-199	Wax	454g	Temporary	Plasticised General Bonding Wax. Melting point 57 - 59 °C. Suitable for a wide range of temporary specimen bonding applications.
0CON-200	Wax	454g/5 ingots	Temporary	Quartz Wax, melting point 66 - 69 °C. Particularly suited to electro-optic and optical materials bonding / mounting applications.
0CON-287	Mounting Resin	1kg	Permanent	Araldite Mounting Resin. Suitable for mounting a wide range of samples in Logitech Annular Saws. For use with Araldite Mounting Hardener.
0CON-288	Mounting Hardener	0.4kg	Permanent	Araldite Mounting Hardener. For use with Araldite Mounting Resin.
0CON-324	Wax	454g	Temporary	Glycol Phthalate. Suitable for bonding semiconductor wafers where high shear strength is required. 71 °C softening point, becomes fluid at around 122 °C.

CLEANING FLUIDS & POWDERS

Code	Type	Pack Size	Description
0CON-178	Ecoclear	3.785 litres	Non-solvent cleaning fluid. Suitable for most sample and substrate cleaning applications including demounting ultra-thin semiconductor wafers.
0CON-177	Bonding Wax Cleaning Powder	5 litres	Non-solvent cleaning powder used as a heat diluted liquid in conjunction with 0CON-193 for demounting wafers from substrates.

GLASS MICROSCOPE SLIDES

Logitech slides meet optical qualities such as flatness, planarity, homogeneity, reflective index and dispersive power to the most exacting industry standards.



GLASS MICROSCOPE SLIDES

Logitech Glass Microscope Slides are used for the permanent mounting of thin rock, concrete and soil thin sections.

These microscope slides are manufactured to stringent production quality control procedures, ensuring flatness and the elimination of bubbles, seeds, striae and other imperfections.

Comprised of high quality sheet glass to give maximum resistance to corrosion, the microscope slides also benefit the user with sand blasted edges for greater safety and ease of handling.

Code	Slide Size	Pack Size	Thickness	Description
0CON-053	100	76 x 51 mm	2 mm	
0CON-102	100	30 x 45 mm	1.6 mm	
0CON-145	100	27 x 46 mm	1.2 - 1.5 mm	
0CON-146	100	35 x 40 mm	1.2 - 1.5 mm	
0CON-148	100	30 x 46 mm	1.2 - 1.5 mm	
0CON-150	100	26 x 46 mm	1.2 - 1.5 mm	
0CON-151	100	28 x 48 mm	1.2 - 1.5 mm	
0CON-152	100	76 x 26 mm	1.2 - 1.5 mm	
0CON-153	100	76 x 51 mm	1.2 - 1.5 mm	
0CON-154	100	76 x 110 mm	1.2 - 1.5 mm	
0CON-155	100	102 x 152 mm	1.2 - 1.5 mm	

High quality glass microscope slides, RI 1.54, finished edges. Highest quality materials are used, suitable for he most stringent of applications.

GLASS COVERSLIPS

Logitech coverslips meet optical qualities such as flatness, planarity, homogeneity, reflective index and dispersive power to the most exacting industry standards.

GLASS COVERSLIPS

Logitech Glass Coverslips protect valuable thin sections and improve optical clarity for transmitted microscopy.

These slide coverslips are specially designed to give high resistance to fogging and microscope mould - even under extreme weather conditions.

Manufactured under close control during all stages of production, the slides thickness conforms to the standard microscope coverslip thickness of 0.170mm.

Code	Size	Pack Size	Description
0CON-156	24 x 44 mm	100	
0CON-157	26 x 46 mm	100	High quality glass produced to exacting standards
0CON-147	34 x 39 mm	100	
0CON-159	74 x 49 mm	100	
0CON-160	74 x 108 mm	100	
0CON-161	75 x 25 mm	100	

CARRIER DISCS & SUBSTRATES

Logitech Glass Carrier Discs are used for the temporary support of both semiconductor and opto-electronic wafers during thinning and polishing operations. Higher density glass is more stable for 6 inch diameter applications and will not distort during the bonding process.

Code	Size	Pack Size	Description
0CON-338	105 mm	1	B270 glass substrate, unlapped.
0CON-336	83 mm	1	B270 glass substrate, 6mm thick, pre-lapped.
0CON-337	105 mm	1	B270 glass substrate, pre-lapped.
0CON-335	160 mm	1	B270 glass substrate, pre-lapped.
0CON-164	83 mm	1	Float glass, flat lapped on one side only.
0CON-165	83 mm	1	Float glass, unlapped parallel.
0CON-166	83 mm	1	Float glass, pre-lapped parallel, maximum error 2µm, thickness 6mm, flatness 2µm
0CON-168	75 mm	1	Float glass, pre-lapped parallel, maximum error 2µm, thickness 6mm, flatness 2µm
0CON-170	105 mm	1	Float glass, unlapped parallel.
0CON-173	105 mm	1	Float glass, pre-lapped parallel, maximum error 4µm, thickness 6mm, flatness 4µm
0CON-179	112 mm	1	Float glass, pre-lapped parallel, maximum error 4µm, thickness 6mm, flatness 4µm
0CON-181	83 mm	1	Float glass, pre-lapped parallel, one face polished, maximum error 2µm, thickness 6mm, flatness 2µm, finished Ra 300nm
0CON-182	105 mm	1	Float glass, pre-lapped parallel, one face polished, maximum error 2µm, thickness 6mm, flatness 2µm, finished Ra 300nm
0CON-339	207 mm	1	B270 glass substrate, 3mm thick, pre-lapped parallel.

WAFER TEMPLATES

Logitech templates are manufactured to our high quality standards. Our templates are made from Fibreglass and are suitable for polishing Ceramic, BK7, Glass, Quartz, Silicate Lens and Silicon.

PRODUCT DATA

Product Type:	Standard Wafer Templates
Material:	Fibreglass
Pocket Depth Range:	0.004 - 0.051 in
Backing Film	
Compressibility:	9.01%

STANDARD TEMPLATES

Code	Pack Size	Description
0CON-494	10	50mm Static Wafer Template - One piece template for wafer O.D. - 50mm, wafer thickness - 300um, Template O.D. - 152mm
0CON-495	10	75mm Static Wafer Template - One piece template for wafer O.D. - 75mm, wafer thickness - 375um, Template O.D. - 152mm
0CON-496	10	100mm Static Wafer Template - One piece template for wafer O.D. - 100mm, wafer thickness - 525um, Template O.D. - 152mm
0CON-497	10	150mm Static Wafer Template - One piece template for wafer O.D. - 150mm, wafer thickness - 625um, Template O.D. - 228mm
0CON-498	10	200mm Static Wafer Template - One piece template for wafer O.D. - 200mm, wafer thickness - 725um, Template O.D. - 254m
0CON-499	10	PP9 Wafer Template Special Instruction - One piece template for PP9 Jig Special Instruction - SI number required
0CON-500	10	DP Template Special Instruction - One piece template for DP Special Instruction - SI number required

GENERAL SUPPLIES

Lubricants, Optical pitches, Coolants, Vacuum Oils and general supplies.

LUBRICANTS, COOLANTS & VACUUM OILS

Logitech Oils are designed to ensure the efficient and smooth functioning of Logitech equipment requiring a source of oil. These oils are produced to a very high standard, therefore safeguarding Logitech machines and components from excessive wear.

Logitech Ultragrade 19 Vacuum Oil is a high quality oil designed to ensure the smooth operation of Logitech machines incorporating a Speedivac or Vacuum Pump.

CC Lube is an effective lubricant for ensuring the smooth operation of the piston components in all Logitech Precision Jigs. Once the jig has been dismantled in accordance with Logitech instructions, CC Lube is easily applied from its syringe.

PRODUCT DATA

Product Type:	CC Lube (semi-solid paste)
Appearance:	White to pale yellow
Boiling Point:	<316 deg °C (600.8 °F)
Flashpoint:	105 deg °C (221 °F)
Grading:	FEPA 42-GB-1984
Melting Point:	260 deg °C (500 °F)
Quantity supplied:	1 x 20ml syringe

Product Type:	Ultragrade 19 Vacuum Oil
Appearance:	Pale yellow to clear
Boiling Point:	380 °C (716 °F)
Flashpoint:	200 °C (392 °F)
Specific Gravity:	0.86
Quantity supplied:	1 litre pack

Code	Product	Pack Size	Description
0CON-223	Hydraulic Oil	1 litre	Hydraulic Oil (Type 22) for use with LD1 Lindear Drive Unit
0CON-319	CC-Lube	20ml	CC-Lube (Jet Lube) oil for PP5, PP6, PP8 and PLJ2 piston lubrication.
0CON-225	DB Oil	5 litres	DB Soluble Oil used as a coolant for GTS1 Saw.
0CON-306	Vacuum Oil	1 litre	Ultragrade 19 Vacuum Oil, for vacuum pumps supplied with LP50, VS2, IU30 & WSBU.
0CON-235	Dressing Stone	12	Dressing Stone for use with GTS1 and CS30 saws.
0CON-241	Keystone Oil Blue Dye	1kg	Keystone Oil Blue Dye, for use when impregnating geological samples with synthetic resins.
0CON-255	Diamond File	1	Diamond file for use with glass lapping plates and glass test blocks.
0CON-285	Ceramic Tiles	5	Unglazed ceramic mounting tiles for use with the APD1 & APD2 saws.
0CON-289	M27 Soluble Oil	1 litre	Oil used as a coolant for the APD1 & APD2 saws.
0CON-316	Heating Oil	1 litre	Heating Oil for Wafer Substrate Bonding Units (WSBUs).

Logitech Ltd.

Erskine Ferry Rd.
Old Kilpatrick
Glasgow
G60 5EU
Scotland, UK

T: +44 (0) 1389 875444
E: enquiries@logitech.uk.com
W: www.logitech.uk.com

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